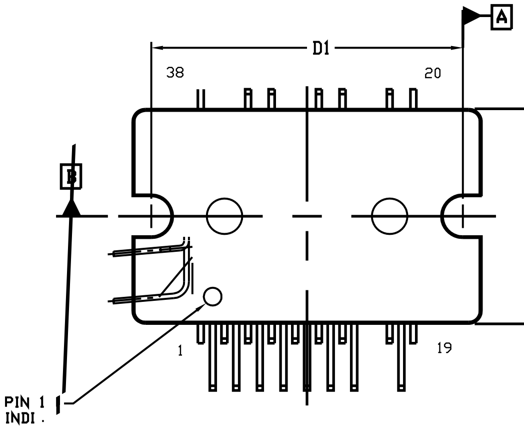
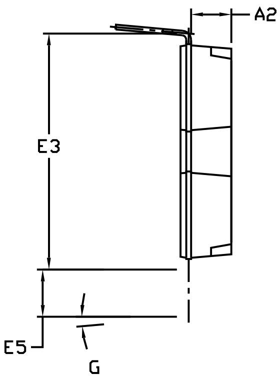
MODULE SPCM24 29.6x18.2 DIP S3

CASE MODBL

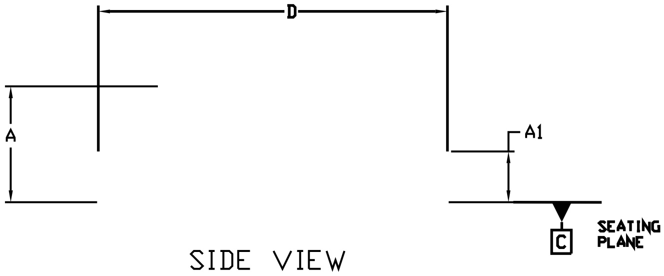
ISSUE A



TOP VIEW



END VIEW



SIDE VIEW

PER.

ASME Y14.5M, 2009.

3. DIMENSION b APPLIES TO THE PLATED LEAD

FROM THE LEAD TIP.

24, 25, 27, 29, 30, 31, 33, 35, 36, AND 37.

DIM	MILLIMETERS	
	MIN.	MAX.
A	9.30	10.30
A1		
A2		
b	0.45	0.70
D		
D1		
D2	-.20	20.20
E	17.70	
E2		
e	1.00 BSC	

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